



GPI711  
#25A  
11/29/99  
O.M.

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: 1711  
Examiner: R. Sargent

In Re PATENT APPLICATION OF

Applicant: LIU et al.

Serial No.: 08/958,460

Filed: October 28, 1997

For: HIGH DENSITY PLASMA  
CHEMICAL VAPOR  
DEPOSITION PROCESS

Atty. Docket: JIA 462

AMENDMENT

**BOX NON-FEE AMENDMENT**

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

In response to the Official Action dated August 19, 1999, please amend the above-referenced application as follows:

IN THE CLAIMS

1. (Amended) A method for forming conducting structures separated by gaps on a substrate, comprising:

providing a substrate and a wiring line layer above the substrate;

forming a first antireflective coating on the wiring line layer;

forming a second antireflective coating on the first antireflective coating,

wherein the first antireflective coating and the second antireflective coating are formed from different materials;

RECEIVED  
NOV 17 1999  
TC 1700 MAIL ROOM

FEE ENCLOSED: \$ 6  
Please charge any further  
fee to our Deposit Account  
No. 18-0002

JD

A